(Temperature=25°C)

Parameter	Symbol	Value	Unit
Forward Current	I_F	5	

LED

Low Level Output Voltage	V_{OL}	I_O

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input On-state Current	$I_{F(ON)}$	7	-	10	mA
Input Off-state Voltage	$V_{F(OFF)}$	0	-	0.8	V
Supply Voltage	V_{CC}	10	-	30	V
Operating Frequency	f	-	-	50	kHz

: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

: Aceramic capacitor(0.1μF) should be connected between pin 6 (V_{CC}) and pin 4 (GND) to stabilize the operation of a high-gain linear amplifier. Otherwise, this photocoupler may not switch properly. The bypass capacitor should be placed within 1 cm of each pin.

: The rise and fall times of the input on-current should be less than 0.5 μs.

: If the rising slope of the supply voltage (V_{CC}) for the detector is steep, stable operation of the internal circuits cannot be guaranteed. Be sure to set 3 V/μs or less for a rising slope of the V_{CC}.

FIG.1: Forward Current vs. Forward Voltage

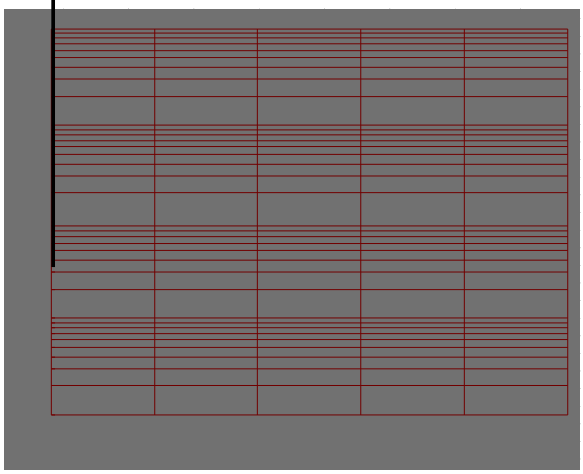


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Low-level Output Voltage vs. Ambient Temperature

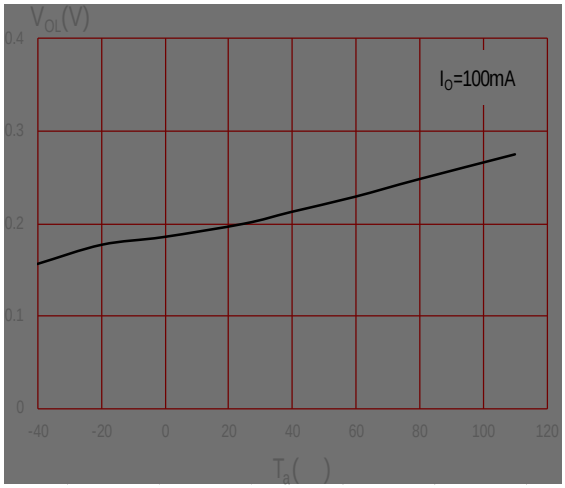


FIG.8: High-level Output Voltage vs. Ambient Temperature

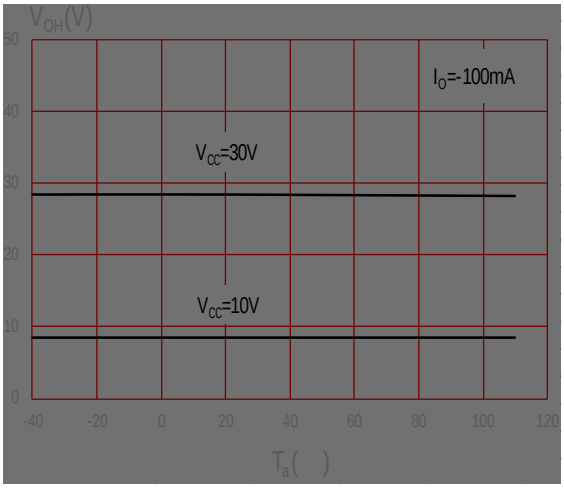


FIG.9: Low-level Output Voltage vs. Peak Low-level Output Current

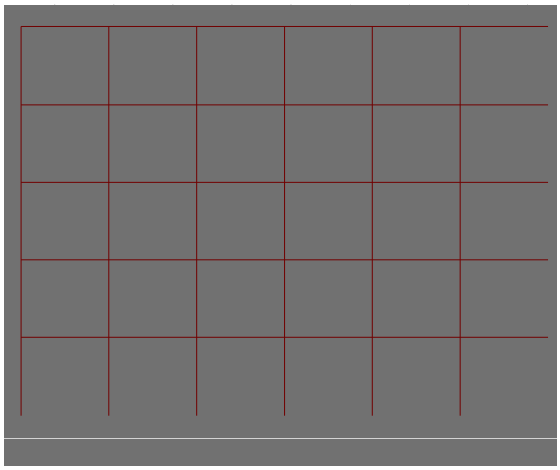
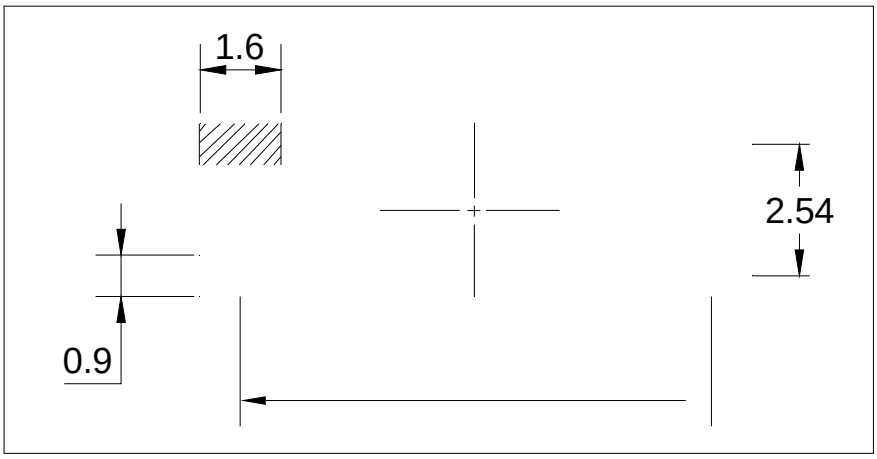


FIG.10: High-level Output Voltage Drop vs. Peak High-level Output Current

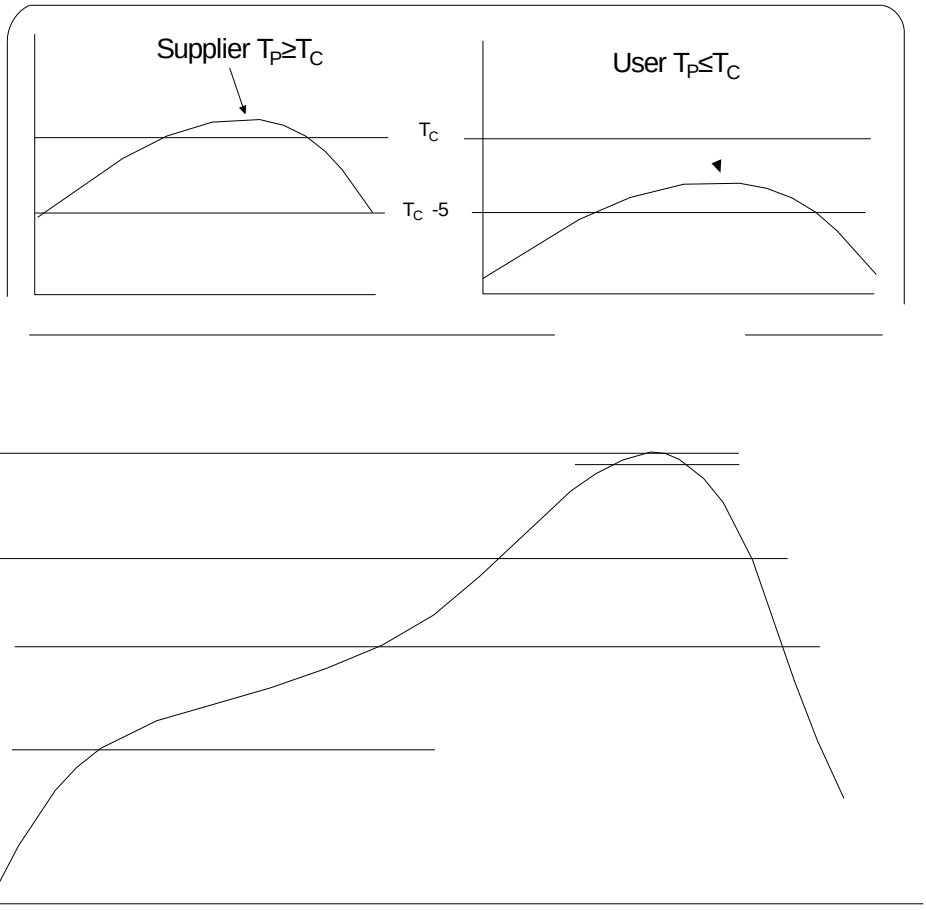
JOCDA1BB


1.6
2.54
0.9

0 .D0P0P1ET6

Dimensions

Ref.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.55	1.60		0.061	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90		8.10	0.311		0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65		1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291		0.299
T	0.35		0.45	0.014		0.018
W	15.80	16.00	16.20	0.622	0.630	0.638


Supplier $T_P \geq T_C$
User $T_P \leq T_C$
T_C
T_C -5

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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